



Material Content Data Sheet



Halogen-Free

Sales Product Name	IQE013N04LM6	Issued	17. May 2021
MA#	MA005406749		
Package	PG-TSON-8-4	Weight*	43.42 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.896	2.06	2.06	20649	20649
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		59	
	non noble metal	zinc	7440-66-6	0.010	0.02		237	
	non noble metal	iron	7439-89-6	0.206	0.47		4743	
	non noble metal	copper	7440-50-8	8.361	19.26	19.76	192573	197612
encapsulation	organic material	carbon black	1333-86-4	0.029	0.07		667	
	plastics	epoxy resin	-	1.491	3.43		34335	
	inorganic material	silicondioxide	60676-86-0	12.953	29.83	33.33	298349	333351
leadfinish	non noble metal	tin	7440-31-5	0.481	1.11	1.11	11081	11081
plating	noble metal	silver	7440-22-4	0.298	0.69	0.69	6866	6866
solder	noble metal	silver	7440-22-4	0.032	0.07		729	
	non noble metal	tin	7440-31-5	0.063	0.15		1457	
	non noble metal	lead	7439-92-1	1.171	2.70	2.92	26962	29148
heat sink clip	inorganic material	phosphorus	7723-14-0	0.004	0.01		102	
	non noble metal	iron	7439-89-6	0.015	0.03		339	
	non noble metal	copper	7440-50-8	14.697	33.86	33.90	338536	338977
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			17	
	non noble metal	iron	7439-89-6	0.002	0.01		57	
	non noble metal	copper	7440-50-8	2.472	5.69	5.70	56940	57014
clip attach	non noble metal	tin	7440-31-5	0.005	0.01		106	
	noble metal	silver	7440-22-4	0.006	0.01		133	
	non noble metal	lead	7439-92-1	0.220	0.51	0.53	5063	5302
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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